

ILC-SCRF WebEx Monthly Meeting

Jan. 23, 2009

Agenda:

- 1) Brief report from PM and GLs
 - 1) Plug-compatibility Document (issued, Dec. 2008)
 - 2) TDP-R&D Plan, draft release 3 (reported to FALC)
- 2) Preparation/Documentation for TILC09/AAP-Review, Tsukuba)
 - 1) High-gradient R&D (S0) plan in 2009 (to be reported to EC)
 - 2) S1, S2 Program
- 3) Plug-compatibility
 - 1) Input coupler task force meeting (Dec. 2008)
- 4) S1-Global guideline and bilateral agreement,
- 5) Plan for visiting Cavity Manufacturers
- 6) etc

Report from PMs

- Reports from PMs
 - Input-Coupler Task Force Meeting (Dec. 2008)
 - Minutes to be distributed
 - Plug-Compatibility Document issued
 - TD-Phase R&D Plan Release 3 (draft issued)
 - AAP preparation
- Report from GLs

Preparation for AAP Review

- Major Context for SCRF
 - S0: High gradient, specially on expected progress to TDP-1, and revisit to the base-line gradient for TDP-2.
 - S1: Progress and Plan for the test, specially on S1-global,
 - S2: Plan for the SCRF system engineering and beam acceleration test,
- Documents due Jan. 31 to PMs
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Preparation for the Documents

- Executive summary (by PM, word & ppt)
- Presentations (by GLs, ppt files)
 - Original Plan, Status, and Expected Progress with in TDP1, and further plan in TDP-2
- Reference documents
 - Major presentations (ppt files),
 - Proceedings
 - Technical notes,
- To be submitted to URL

Process to AAP Review

Jan. 31, Review document submitted to PMs

Feb. Updated b/w PMs/GLs

Feb. 28, Submitted to AAP

April 10 Finalized

April 17-1 Review

Plug Compatibility Issues

- Input-coupler Task-Force Meeting (Dec. 2008)
 - Minutes to be distributed
 - Thanks for Jim and Tetsuo for their effort to prepare for the minutes draft, and apology for my late responding,
 - Possible interface conditions
 - Cold-flange with either 40 or 60 mm dia. Flange
 - Intermediate flange >> Additionally proposed,
 - Warm-end flange

S1-Global Agreement

- A general, technical guideline by PMs
 - Three regional participations
 - 2 cavities from DESY, 2 cavities from FNAL, 4 from KEK
 - A half cryomodule from INFN, another half from KEK
 - Assembly and Tests at KEK site,
 - Participations from DESY, FNAL, KEK
 - Assembly to start early 2010, and test start in middle 2010,
 - Test need to be completed by the end of 2010,
 - Progress, Presentation/Reports will be shared by three regions,
- Bilateral agreements to be agreed between laboratories,
 - First one for cryomodule, done between INFN-KEK
 - Second one to be discussed in next week at DESY,

Plan for visiting Cavity Vendors

- Visiting Plan (to be settled)
 - AES: Feb. 26, Niowave: Feb. 27
 - ACCEL and Zanon in the first week of March
 - MHI: March 11,
- Objectives
 - To learn technical status at the vendors
 - To inform TD-Phase R&D Plan, and plug-compatible conditions
 - To establish good communications and reliable relations,
- Process
 - First to discuss with Retional Directors,
 - Second to discuss with Institutional Leader and contact persons,
 - Plan to visit